

Analog Switch

REJ03D0197–0700Z (Previous ADE-205-308E (Z)) Rev.7.00 Jan.29.2004

Description

The HD74HCT1G66 is high-speed CMOS analog switch using silicon gate CMOS process. With CMOS low power dissipation, it provides high speed. The device has low ON resistance for good transfer characteristics and can take wide range of input voltage.

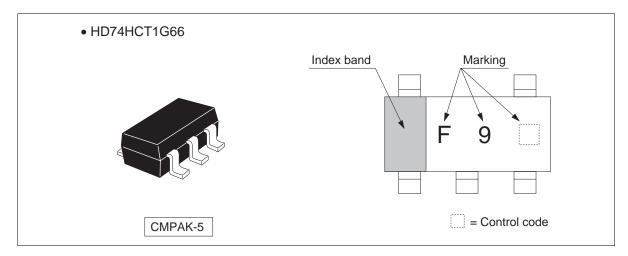
Features

- The basic gate function is lined up as Renesas uni logic series.
- Supplied on emboss taping for high-speed automatic mounting.
- Control input is TTL compatible input level. Supply voltage range : 4.5 to 5.5 V Operating temperature range : -40 to +85°C
- $|I_{OH}| = I_{OL} = 2 \text{ mA (min)}$
- Ordering Information

Part Name	Package Type	Package Code	Package Abbreviation	Taping Abbreviation (Quantity)
HD74HCT1G66CME	CMPAK-5 pin	CMPAK-5V	СМ	E (3,000 pcs/reel)



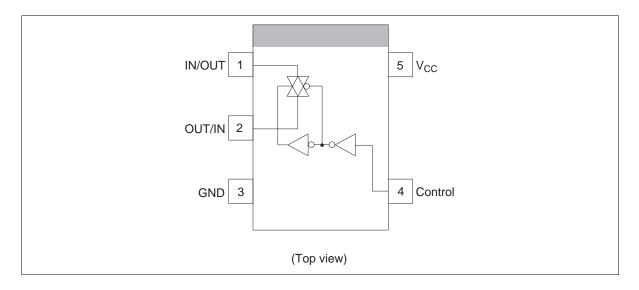
Outline and Article Indication



Function Table

Control	Switch
L	OFF
Н	ON
H : High level	
L : Low level	
$GND \le V_{IN} \le V_{CC}$	
$GND \le V_{OUT} \le V_{CC}$	

Pin Arrangement





Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Test Conditions		
Supply voltage range	V _{CC}	-0.5 to 7.0	V			
Input voltage range *1	VI	-0.5 to V _{CC} + 0.5	V			
Output voltage range * ^{1, 2}	Vo	-0.5 to V _{CC} + 0.5	V	Output : H or L		
Input clamp current	I _{IK}	±20	mA	V_{I} < 0 or V_{I} > V_{CC}		
Output clamp current	l _{ок}	±20	mA	V_0 < 0 or V_0 > V_{CC}		
Continuous output current	lo	±25	mA	V_0 = 0 to V_{CC}		
Continuous current through V_{CC} or GND	I_{CC} or I_{GND}	±25	mA			
Maximum power dissipation at Ta = 25°C (in still air) $*^3$	P _T	200	mW			
Storage temperature	Tstg	–65 to 150	°C			

Notes: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

1. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. This value is limited to 5.5 V maximum.

3. The maximum package power dissipation was calculated using a junction temperature of 150°C.

Recommended Operating Conditions

Item	Symbol	Min	Max	Unit	Test Conditions
Supply voltage range	V _{CC}	4.5	5.5	V	
Input voltage range	VI	0	5.5	V	
Output voltage range	V _{I/O}	0	Vcc	V	
Input rise / fall time (Control input 0.3 V to 2.7 V)	t _r , t _f	0	500	ns	V_{CC} = 4.5 to 5.5 V
Operating temperature	Та	-40	85	°C	

Note: Unused or floating control inputs must be held high or low.



Electrical Characteristics

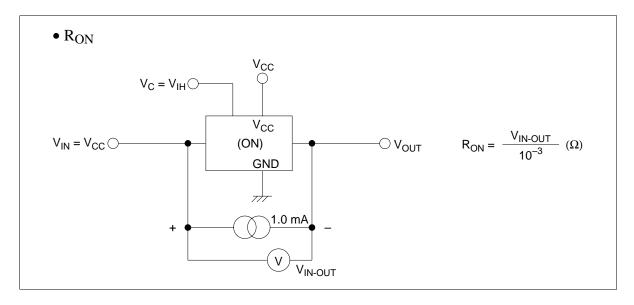
		Vcc	Ta = 2	25°C	Ta = −40 to 85°C		0 to 85°C				
ltem	Symbl	(V)	Min	Тур	Max	Min	Max	Unit	Test Conditions		
Input voltage	V _{IH}	4.5 to 5.5	2.0	_	_	2.0	_	V	Control input only		
	VIL	4.5 to 5.5	—		0.8	—	0.8	-			
On resistance	R _{ON}	4.5 to 5.5	_	90	160		180	Ω	$V_{C} = V_{IH}$ $V_{IN} = V_{CC}$ or GND $I_{T} = 1 \text{ mA}$		
Peak on resistance	R _{ON} (p)	4.5 to 5.5		125	200		250	Ω	$V_{C} = V_{IH}$ $V_{IN} = 0 \text{ to } V_{CC}$ $I_{IN/OUT} = 1 \text{ mA}$		
Leak current	I _S (off)	5.5	_	_	±0.1	_	±1.0	μA	$\label{eq:VC} \begin{split} V_{C} &= V_{IL} \\ V_{IN} &= V_{CC}, \ V_{OUT} = GND \\ or \ V_{IN} &= GND, \\ V_{OUT} &= V_{CC} \end{split}$		
	I_{S} (on)	5.5	_	_	±0.1	_	±1.0	μA	$V_{C} = V_{IH}$ $V_{IN} = V_{CC}$ or GND		
Input current	I _{IN}	5.5		_	±0.1	_	±1.0	μA	$V_{IN} = V_{CC}$ or GND		
Operating current	Icc	5.5	_	_	1.0	_	10.0	μA	$V_{IN} = V_{CC}$ or GND		
Quiescent supply current	I _{CCT}	5.5	_	—	2.0		2.9	mA	V_{C} = 2.4 V, V_{IN} (switch) = V _{CC} or GND		



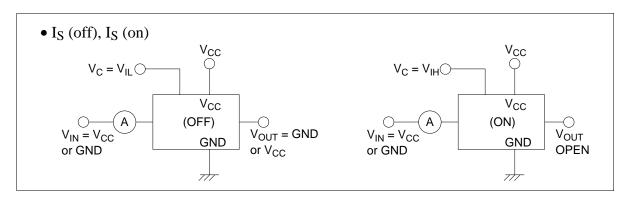
Switching Characteristics

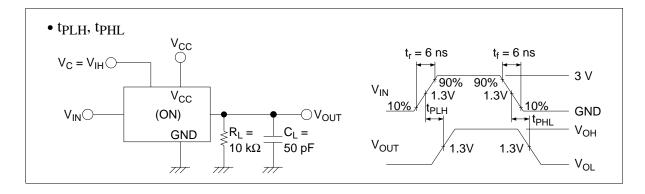
		Vcc	Ta = 2	25°C		Ta = -4	10 to 85°C		Test
ltem	Symbl	(V)	Min	Тур	Max	Min	Max	Unit	Conditions
Propagation delay time	t _{PLH} , t _{PHL}	4.5		4	10	_	13	ns	R _L = 10 kΩ
Output enable time	t_{ZH},t_{ZL}	4.5	_	10	23		29	ns	R_L = 1 k Ω
Output disable time	t_{HZ}, t_{LZ}	4.5	_	14	23		29	ns	$R_L = 1 k\Omega$
Maximum control frequency		4.5	_	30	_	_	_	MHz	
Control input capacitance	C _{IN}		_	2.5	5	_	5	pF	
Switch I/O capacitance	C _{IN/OUT}		_	2.5			—	pF	
Feed through capacitance	$C_{\text{IN-OUT}}$		_	0.5	_	_	_	pF	
Power dissipation capacitance	C _{PD}		_	5	_		—	pF	

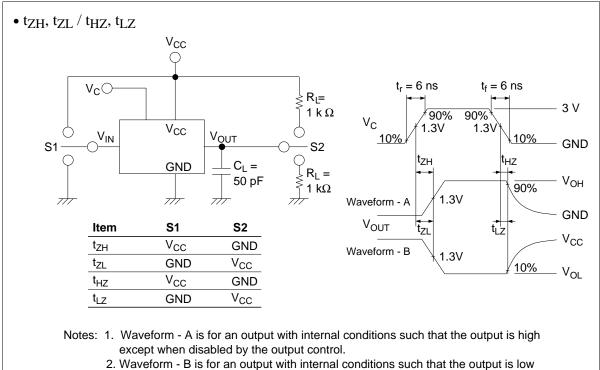
Test Circuit





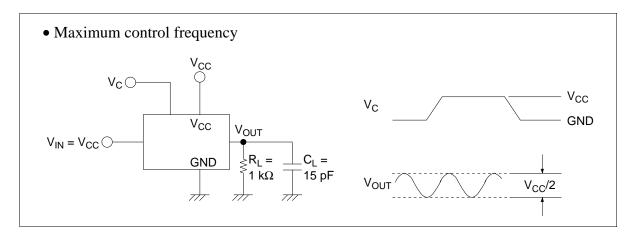


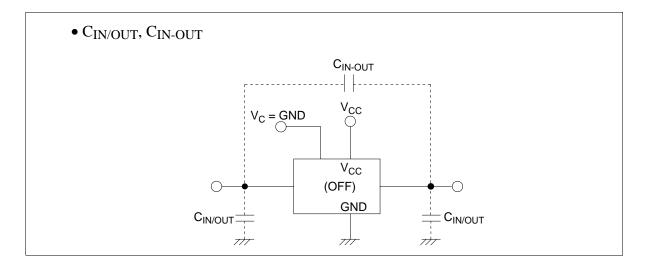




except when disabled by the output control.

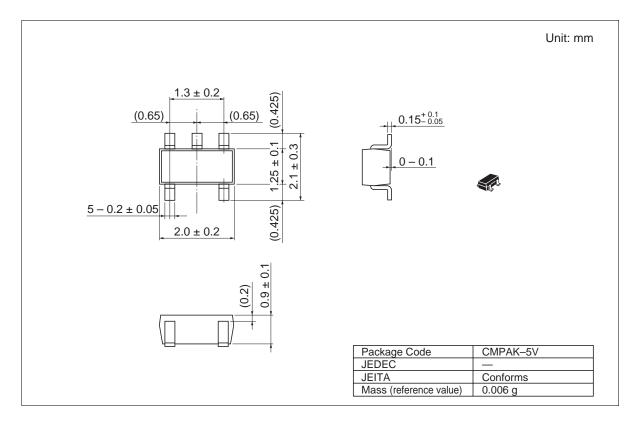
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Package Dimensions





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